PCN: V16-003-E47540-MH

Product Change Notice

Issue Date: 12 February, 2016

Change Type:
Key component changes

Parts Affected:
16G Fibre Channel SFP+ LW, 1310nm Single mode

Current Part Number	New Part Number
AFCT-57F5ATMZ	AFCT-57F3ATMZ
AFCT-57F5NMZ	AFCT-57F3NMZ
AFCT-57F5TMZ	AFCT-57F3TMZ

Description and Extent of Change:
New TOSA design with DFB laser from Broadcom Limited's Breinigsville, PA fab location.

Reason for Change:
New TOSA qualification.

Effect of Change on Fit, Form, Function, Quality, or Reliability:
There is no change to form, fit, function, quality and reliability of the products. The device specification and manufacturing process will be same as the current products.

Effective Date of Change:
Product shipments using this change will begin on or after May 16, 2016 (WW1620), or earlier with customer approval. Timing of shipment will depend on customer demand and inventory on-hand of current products.

Recommended Actions to be Taken by Customer:

1. Module-level qualification is recommended. Foxconn Interconnect Technology (FIT) will make samples available by March 15, 2016 and will begin shipment of new 16G LW SFP+ products upon successful customer qualification starting May 16, 2016. Please return any response as soon as possible, but not to exceed 90 days.

2. Sample requests must specify the PCN # stated above and shall be placed by your Broadcom Field Sales Representative through the FOMFGS ordering system.

Qualification Data:

Qualification with up to 2,000-hour data of the following tests has been completed:

Leg	Test	Reference	Stress Condition	S/S	Expected Result
1	High Temperature Operating Life (HTOL)	Section 5.18 (GR-468-CORE)	Ta = 85°C, Vcc=3.3V Qual Release: 2000Hrs	11	0 Failures @ 2000hrs
2	High Temperature Storage (HTS)	Section 5.18 (GR-468-CORE)	Ta = 100°C Qual Release: 2000Hrs	11	0 Failures @ 2000hrs
3	Biased Damp Heat (BDH)	MIL-STD-202 Method 103	Ta = 85°C, RH = 85%, Vcc=3.3V Qual Release: 1000Hrs	11	0 Failures @ 1000hrs
4	Un-Biased Damp Heat (uBDH)	MIL-STD-202 Method 103	Ta = 85°C, RH = 85% Qual Release: 1000Hrs	11	0 Failures @ 1000hrs
5	Biased Cyclic Moisture Resistance (BCMR)	MIL-STD-883 Method 1004	Ta = -10°C to +65°C, Biased, Power On/Off @30min, 95%RH Qual Release: 20 Cyc	11	0 Failure @ 20 Cyc
6	Temperature Cycling (TMCL)	MIL-STD-883 Method 1010	Ta = -40°C/100°C 15 min. dwell @ Cold & Hot Temp 5 min. Transfer Qual Release: 500 Cyc	11	0 Failure @ 500 Cyc
7	Low Temperature Storage (LTS)	GR-468-CORE	Ta= -40°C Qual Release: 72Hrs	11	0 Failure @ 72hrs
8	Thermal Shock (TS)	MIL-STD-883 Method 1011.9	Ta= -40°C/100°C 5 min dwell @ Cold & Hot Temp 10 s transfer Qual Release: 20 Cyc	11	0 Failure @ 20 Cyc
9a	Mechanical Shock (MS)	MIL-STD-883 Method 2002B	1500g, 0.5ms, 5 shock/axis, 6 axis	11	0 Failure
9b	Mechanical Vibration (MV)	MIL-STD-883 Method 2007	20g, 20 to 2000Hz, 3 axis, 4min/cycle, 4cycle/axis	11	0 Failure
10	ESD – HBM	JESD22-A114-B	1KV (High Speed Pins) 2KV (Low Speed Pins)	6	0 Failure @ 1KV (High Speed Pin) 0 Failure @ 2KV (Low Speed Pins)

These changes have been reviewed and approved by FIT engineers and managers per FIT's procedure.

Please contact your Broadcom Limited field sales engineer or Contact Center for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.